ABSTRACT OF THE DISCLOSURE

There is provided a semiconductor laser device containing a laser driver capable of implementing downsizing, thinning and cost reduction of equipment using the laser device. In the semiconductor laser device containing a laser driver, a semiconductor laser element, a laser driver for driving the laser element, and a signal detection part for performing photoelectric conversion are mounted on a common mount surface of a lead frame and moreover accommodated in a common package. Upward of the semiconductor laser element is provided a hologram element for transmitting laser light emitted by the laser element toward a recording medium and then diffracting toward the signal detection part the laser light reflected by the recording medium. The laser driver and the signal detection part are disposed on both sides with respect to an optical axis of the laser element.